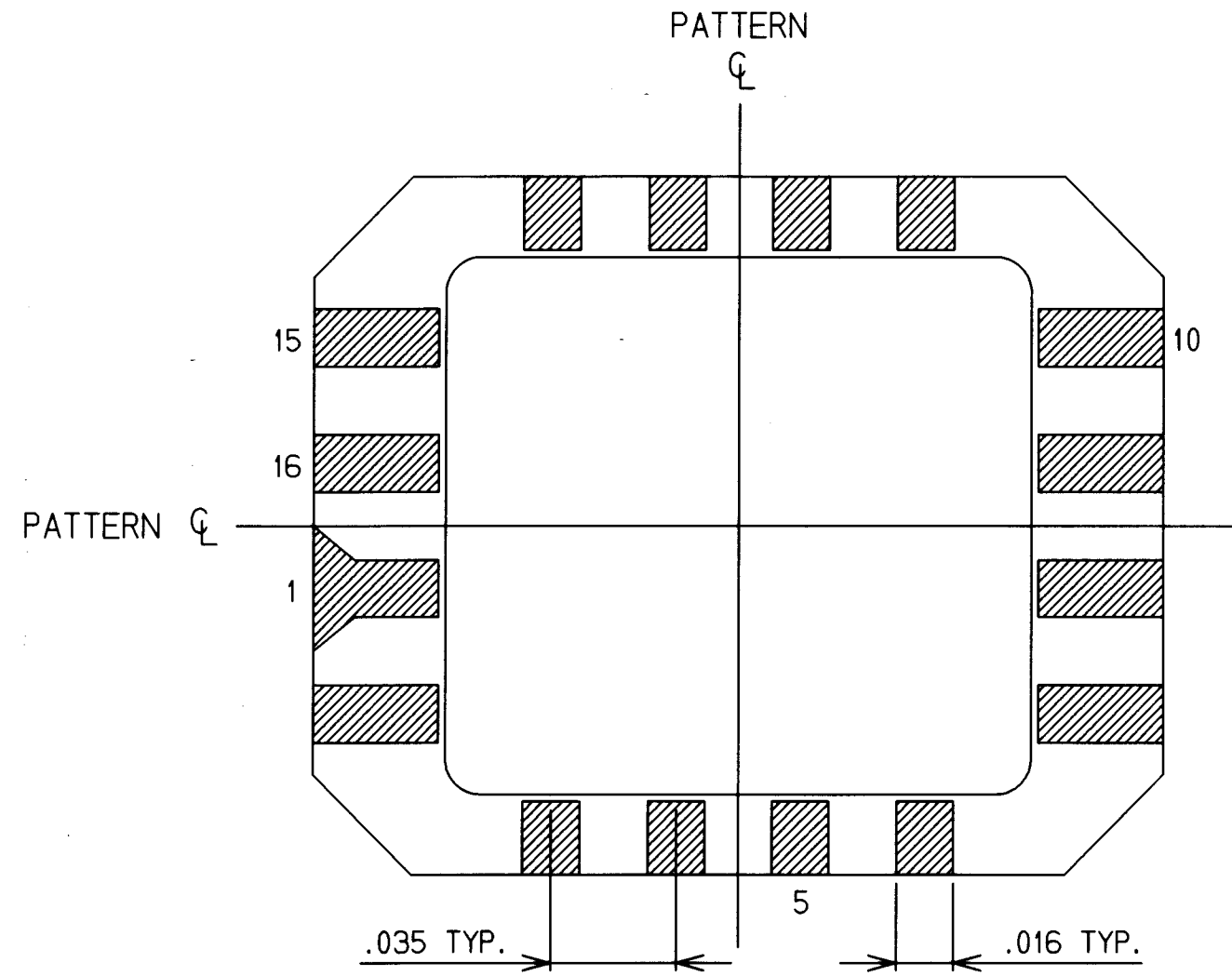


NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

MODIFICATION A REDRAWN (CONVERTED CAD DATA) ADDED: SHEET 2/2 CHANGED						NAME	16 LEAD FLAT PACKAGE	TOLERANCE	±.005	FW016S435-1 S=0 D=0	
						SCALE	8/1	MATERIAL	AS INDICATED	THIRD ANGLE PROJECTION	DRAWN
DATE	OCT. 27 '84	DRAWN	K. I.	CHECKED	H.S./S.F.	APPROVED	T. A.				APR. 29 '86
						KYOCERA	KYOCERA CORPORATION		DRAWING NO.		SHEET
							KYOTO JAPAN		KD-F86435-A		1/2



BONDING PATTERN

MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					16 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED	K. I	H.S/S.F	T. A	OCT. 27. '94
					SCALE 20/1	MATERIAL				
									THIRD ANGLE PROJECTION	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET
							KD-F86435-A		2/2	